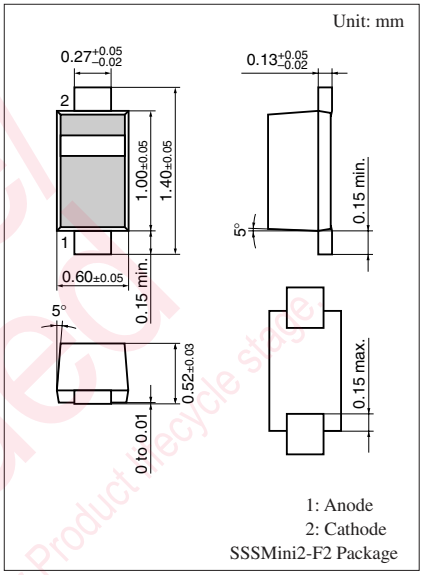
MA27E02

Silicon epitaxial planar type

For cellular phone



Marking Symbol: G

■ Features

- High-frequency wave detection is possible.
- Low forward voltage V_F
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25°C$

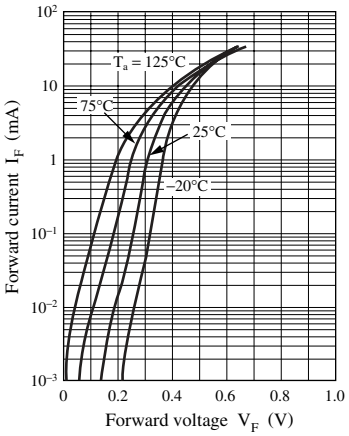
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Maximum peak reverse voltage	V_{RM}	20	V
Forward current	I_F	35	mA
Peak forward current	I_{FM}	100	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

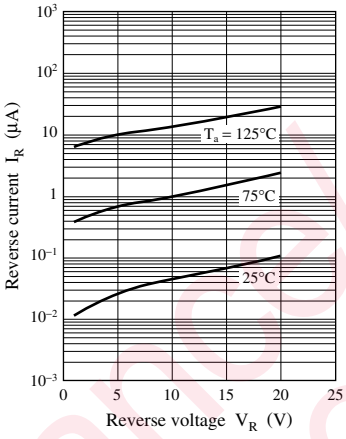
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 1$ mA			0.40	V
	V_{F2}	$I_F = 35$ mA			1.0	V
Reverse current	I_R	$V_R = 15$ V			200	nA
Terminal capacitance	C_t	$V_R = 0$ V, f = 1 MHz			1.2	pF
Forward dynamic resistance	r_f	$I_F = 5$ mA		9		Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Rated input/output frequency: 2 GHz

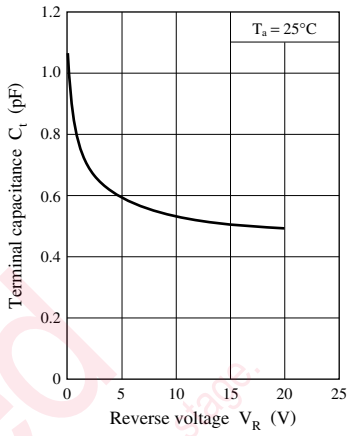
I_F — V_F



I_R — V_R



C_t — V_R



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Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.

(6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.